



RECOMMENDED P.C. B LAYOUT
THICKNESS=1.0mm

NOTE:

- MATERIAL:
HOUSING:HIGH TEMPERATURE THERMOPLASTIC,UL94V-0
TERMINAL:COPPER ALLOY,THICKNESS = 0.25 mm
- PLATING:
CONTACT:GOLD OVER 50u" MIN NICKEL UNDERPLATE
SOLDER TAIL:75u"MIN TIN 50u" MIN NICKEL UNDERPLATE
GOLD SPECIFICATION: a G/F, b 15u", c 30u"
- ELECTRONICAL SPECIFICATION:
CURRENT RATING:1.5 AMPERE PER CONTACT
CONTACT RESISTANCE:30 MILLIOHMS MAX.
INSULATION RESISTANCE:1000 MEGOHMS MIN.
DIELECTRIC WITHSTANDING VOLTAGE:500 VDC.
OPERATING TEMPERATURE:-40C~+85C

DIMENSIONS TOLERANCE METRIC .0=±0.30 .00=±0.20 .000=±0.10 ANG.=±2°	單位(UNITS)	MM	處	SEE NOTE	審核(CH'K)	Calvin	國名(NAME) MICRO SATA 7+7+2P Reverse		WISCONN Technology Co., Ltd Tel:02-2742-1798 Fax:02-2742-1898							
	數量(QT'Y)	N/A	繪圖(DRAW)	Johnson	核准(APP'D)	Selena	料號(PART NUMBER)	WSTAM-1615LBSR-R								
	材料(MT'L)	SEE NOTE	設計(DE'N)	Mike	日期 DATE)	OCT.15.2007	圖號(DRAW NUMBER)	T006	比例(SCALE)	1/1	圖紙(SIZE)	A4	頁次(SHEET)	1	版次(REV.)	A
								圖檔(FILE NAME .DWG)								